[Notes] FSP 6.0.0 not compatible with Reality AI Utilities and QE for OTA

R20TS1159EJ0100 Rev.1.00 Jul. 20, 2025

Outline

When using either Reality AI Utilities or QE products on e² studio, note the following points.

- The following features may not function as intended on e² studio with FSP 6.0.0.
 - o Both Reality Al Utilities Plugin and Standalone: Hardware in Loop (HIL) Testing.
 - QE for OTA: Initial Firmware Creation with RA MCUboot.

1. Note on usage on e² studio with FSP 6.0.0

1.1 About Reality Al Utilities

1.1.1 Applicable Products

- Reality AI Utilities V2.2.0
- FSP 6.0.0

1.1.2 Applicable Devices

• RA Family except RA8P1

1.1.3 Detail

Project fails to build in Hardware in Loop Testing plug-in.

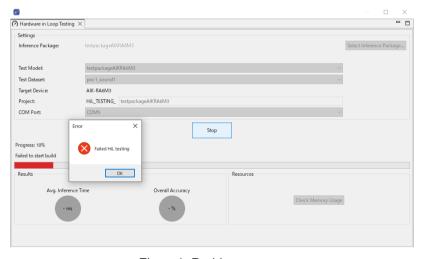


Figure1: Problem screen

1.1.4 Condition

Using Reality Al Utilities v2.2.0 Hardware in loop testing with FSP 6.0.0.

1.1.5 Workaround

Install FSP5.x instead. At least FSP5.7 or later.

Release v5.7.0 · renesas/fsp



1.1.6 Issue Resolution Timeline

This problem will be fixed in the next version. (Scheduled to be released in Aug 2025.)

1.2 About QE products

1.2.1 Applicable Products

- QE for OTA V2.2.0
- FSP 6.0.0

1.2.2 Applicable Devices

RA Family

1.2.3 Detail

An initial firmware with MCUboot fails to create after a project built.

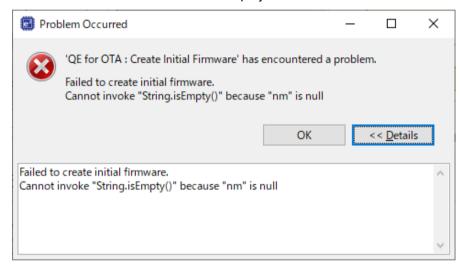


Figure2: Problem screen

1.2.4 Condition

When you try to create an initial firmware with MCUboot using QE for OTA V2.2.0 and FSP 6.0.0.

1.2.5 Workarounds

You can work around this issue in one of the following ways:

- Instead of using QE for OTA, refer to the FSP documentation to create the initial firmware and update the firmware.
- If you are using QE for OTA, use it in combination with FSP 5.9.0.

1.2.6 Issue Resolution Timeline

This problem will be fixed in the next version. (Scheduled to be released in Dec 2025.)



Revision History

		Description	
Rev.14	Date	Page	Summary
1.00	Jul.20.2025	-	First edition issued

Renesas Electronics has used reasonable care in preparing the information included in this document, but Renesas Electronics does not warrant that such information is error free. Renesas Electronics assumes no liability whatsoever for any damages incurred by you resulting from errors in or omissions from the information included herein.

The past news contents have been based on information at the time of publication. Now changed or invalid information may be included.

The URLs in the Tool News also may be subject to change or become invalid without prior notice.

Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu, Koto-ku, Tokyo 135-0061, Japan www.renesas.com

Trademarks

Renesas and the Renesas logo are trademarks of Renesas Electronics Corporation. All trademarks and registered trademarks are the property of their respective owners.

Contact information

For further information on a product, technology, the most up-to-date version of a document, or your nearest sales office, please visit: www.renesas.com/contact/

 $\hbox{@ 2025 Renesas Electronics Corporation. All rights reserved.}$

TS Colophon 4.3